



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPTG025N10NM5	Issued	17. February 2022
MA#	MA005698744		
Package	PG-HSOG-8-1	Weight*	704.71 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.510	0.64	0.64	6399	6399
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		191	
	non noble metal	copper	7440-50-8	134.219	19.05	19.08	190461	190709
wire	non noble metal	aluminium	7429-90-5	14.082	2.00	2.00	19983	19983
encapsulation	inorganic material	zinc oxide	1314-13-2	2.633	0.37		3736	
	miscellaneous	miscellaneous	-	10.530	1.49		14943	
	plastics	epoxy resin	-	39.489	5.60		56036	
	inorganic material	silicon dioxide	60676-86-0	210.606	29.89	37.35	298857	373572
lead finish	non noble metal	tin	7440-31-5	8.309	1.18	1.18	11791	11791
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	311	312
solder	non noble metal	tin	7440-31-5	0.077	0.01		110	
	noble metal	silver	7440-22-4	0.097	0.01		137	
	non noble metal	lead	7439-92-1	3.695	0.52	0.54	5244	5491
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		118	
	non noble metal	iron	7439-89-6	0.276	0.04		392	
	non noble metal	copper	7440-50-8	275.705	39.13	39.18	391233	391743
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com